DB3X313N

Silicon epitaxial planar type

For small current rectification

■ Features

- Low forward voltage V_F and small reverse current I_R
- Low terminal capacitance C_t
- Halogen-free / RoHS compliant
 (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

■ Marking Symbol: 4N

■ Basic Part Number

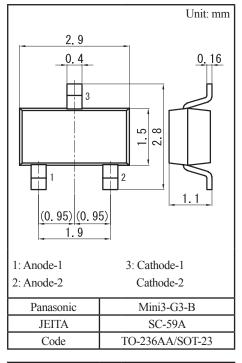
Dual DB2J313 (Common Cathode)

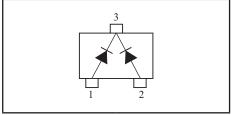
Packaging

DB3X313N0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit		
Reverse voltage		V _R	30	V	
Repetitive peak reverse voltage	V _{RRM}	30	V		
Forward current (Average)	Single	т.	200	mA	
	Double *1	$I_{F(AV)}$	130		
Peak forward current	Single	т	300	mA	
	Double *1	I_{FM}	220		
Non-repetitive peak reverse surge voltage *2	Single	-	1.0	A	
	Double *1	I_{FSM}	0.7		
Junction temperature		T_{j}	125	°C	
Operating ambient temperature		T _{opr}	-40 to +85	°C	
Storage temperature	T _{stg}	-55 to +125	°C		





Note) *1: Value of each diode in double diodes used.

*2: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

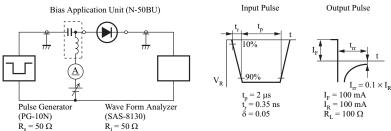
■ Electrical Characteristics $T_a = 25$ °C±3°C

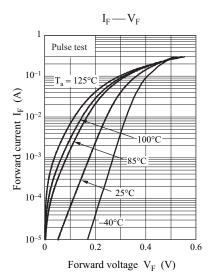
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 200 \text{ mA}$			0.55	V
Reverse current	I_R	$V_R = 30 \text{ V}$			50	μΑ
Terminal capacitance	C _t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		3.8		pF
Reverse recovery time *1	t _{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$		1.5		ns

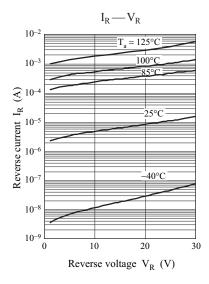
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

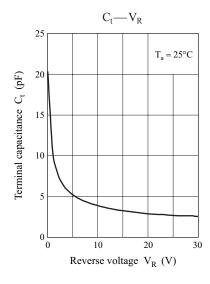
- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 1 GHz

*1: t_{rr} measurement circuit





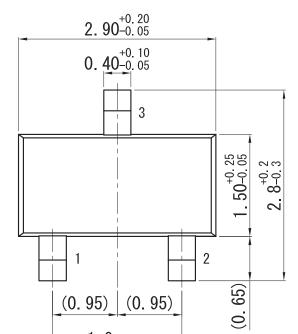


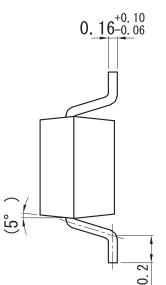


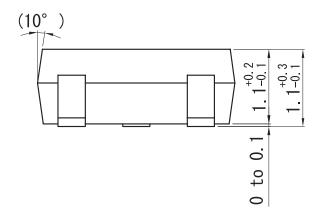
Ver. CED 2

Unit: mm

Mini3-G3-B

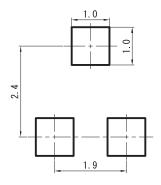






 1.9 ± 0.1

■ Land Pattern (Reference) (Unit: mm)



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